

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method of reclaiming silicon wafers ~~which includes~~
comprising:

a film removal process[[],]; a polishing process[[],]; ~~and~~ a cleaning process[[],]; and
~~wherein the method comprises a heating/removal process for heating the silicon wafer at 150-~~
~~300.degree. C. for 20 minutes-5 hours and for removing the surface part of the silicon wafer,~~
between the film removal process and the polishing process,

wherein the heating/removal process comprises heating the silicon wafer at 150-300
°C for 20 minutes to 5 hours and removing a surface part of the silicon wafer.

Claim 2 (Currently Amended): The method of reclaiming silicon wafers according to
claim 1, wherein the heating/removal process ~~includes~~ comprises a mechanical removal
process.

Claim 3 (Currently Amended): The method of reclaiming silicon wafers according to
claim 1, wherein the heating/removal process ~~includes~~ comprises a chemical removal
process.

Claim 4 (Original): The method of reclaiming silicon wafers according to claim 3,
wherein the chemical removal process is performed using alkali hydroxides and/or alkali
carbonates.

Claim 5 (Currently Amended): The method of reclaiming silicon wafers according to
claim 1, wherein the method comprises both

an immersion process ~~for~~ comprising chemically processing the silicon wafer with a chemical processing liquid; a silicon wafer and

a the heating/removal process ~~for~~ comprising heating the silicon wafer at 150-300 °C for 20 minutes~~[[-]]~~ to 5 hours and ~~for~~ removing a surface part of the silicon wafer ~~are~~ included between the film removal process and the polishing process.

Claim 6 (Currently Amended): The method of reclaiming silicon wafers according to claim 5, wherein a the chemical processing liquid ~~is defined as~~ comprises:

a hydrogen peroxide aqueous solution; a mixed solution of a hydrogen peroxide aqueous solution, an ammonia aqueous solution, and water;

a mixed solution of a hydrogen peroxide aqueous solution, hydrochloric acid, and water; alkali hydroxide aqueous solution; or

an alkali carbonate aqueous solution.

Claim 7 (Currently Amended): The method of reclaiming silicon wafers according to claim 5, wherein the heating/removal process ~~includes~~ comprises a mechanical removal process.

Claim 8 (Currently Amended): The method of reclaiming silicon wafers according to claim 5, wherein the heating/removal process ~~includes~~ comprises a chemical removal process.

Claim 9 (Original): The method of reclaiming silicon wafers according to claim 8, wherein the chemical removal process is performed using alkali hydroxides and/or alkali carbonates.

Claim 10 (Currently Amended): The method of reclaiming silicon wafers according to claim 6, wherein the heating/removal process ~~includes~~ comprises a mechanical removal process.

Claim 11 (Currently Amended): The method of reclaiming silicon wafers according to claim 6, wherein the heating/removal process ~~includes~~ comprises a chemical removal process.

Claim 12 (Original): The method of reclaiming silicon wafers according to claim 11, wherein the chemical removal is performed using alkali hydroxides and/or alkali carbonates.

Claim 13 (Original): The method of reclaiming silicon wafers according to claim 12, wherein the alkali hydroxide and/or carbonate are selected from a group consisting of potassium hydroxide, potassium carbonate, sodium hydroxide, sodium carbonate, and quaternary alkyl ammonium hydroxides.